CLAIM AMENDMENTS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1 (original). A method for manufacturing a housing for a chip having a micromechanical structure, comprising the following steps:

(a) providing a first basis which comprises a photolithographically structurable layer on at least a partial region of a main face;

(b) photolithographically structuring the first photolithographically structurable layer to obtain a cover for the micromechanical structure;

(c) providing a chip comprising the micromechanical structure, which is arranged at a main face of the chip between the first contact elements;

(d) applying a second photolithographically structurable layer on at least a partial region of the main face of the chip;

(e) photolithographically structuring the second photolithographically structurable layer for generating a recess surrounded by a wall in the photolithographically structurable layer in the region of the micromechanical structure and for exposing the first contact elements;

(f) merging the first basis and the chip in a way so that the micromechanical structure and the cover are facing each other and are aligned with each other, so that the recess is closed by the cover, whereby an on-chip cavity is obtained;

(g) removing the first basis in order to obtain a chip comprising an on-chip cavity;

(h) merging a second basis and the chip comprising the on-chip cavity in such a way that the first contact elements are connected to the second basis via a conductive structure; and

(i) removing the second basis for exposing the conductive structure.

2 (original). The method according to claim 1, wherein the second basis comprises second contact elements on the main face of the second basis, wherein the step (h) is performed

such that first and the second contact elements are respectively connected to each other.

3 (original). The method according to claim 1, wherein the second contact elements consist of nickel islands.

4 (original). The method according to claim 1, which further comprises the step of applying soldering pellets onto the third contact elements prior to step (h).

5 (original). The method according to claim 1, wherein the second basis consists of copper.

6 (original). The method according to claim 5, wherein the step (i) includes etching away the second basis.

7 (original). The method according to claim 1, wherein the first and/or the second photolithographically structurable layer consists of a photosensitive epoxy resin.

8 (original). The method according to claim 1, wherein the step (a) comprises applying the first photolithographically structurable layer on at least a partial region of a main face of a first basis, on which already a sacrificial layer

is located and wherein the step (g) comprises etching away the sacrificial layer.

9 (original). The method according to claim 1, wherein the step (h) is performed such that after merging a gap between the cover and the second basis results.

10 (original). The method according to claim 1, wherein the step (h) is performed such that after merging the cover and the second basis contact each other.

11 (original). The method according to claim 1, further comprising the step of closing the structure resulting after step (h) from the chip comprising the on-chip cavity and the second basis comprising a covering layer, whereby after step (i) the conductive structure is exposed at an exposed main face of the structure close by the step of closing.

12 (currently amended). The method according to ~~claim 1~~ claim 11, wherein the covering layer consists of a plastics material.

13 (original). The method according to claim 1 which comprises providing a stud bumping structure on the first contact elements prior to step (h).